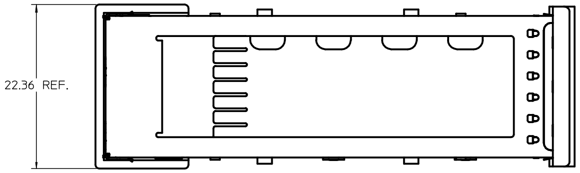
Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

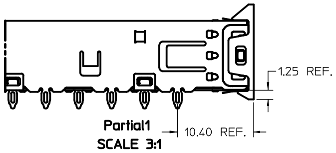
With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

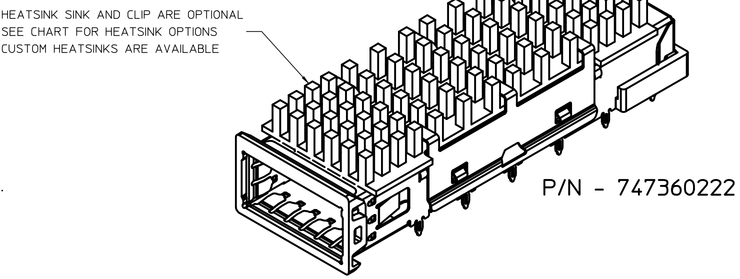
Contact us

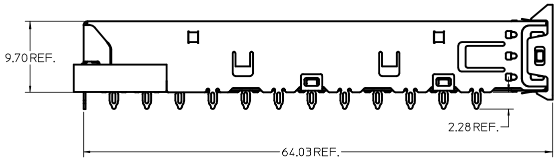
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

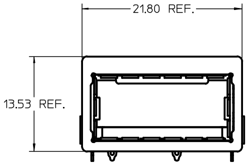


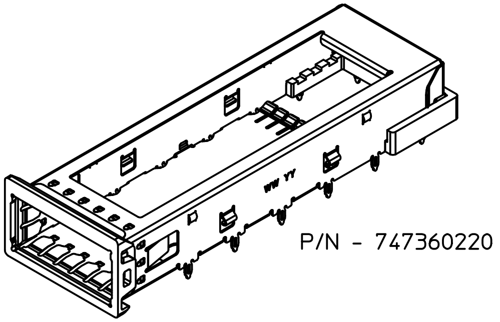


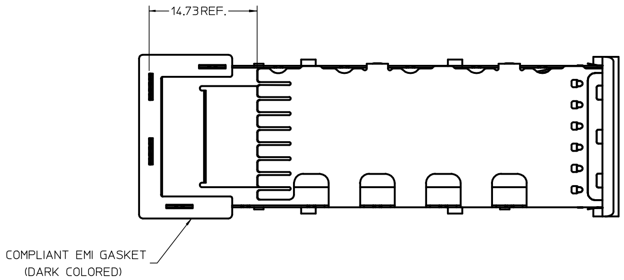
Partial1
SCALE 3:1







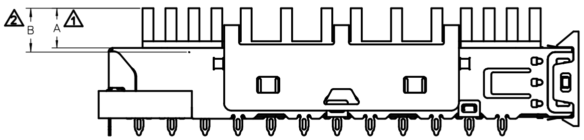




PART NUMBER FOR XFP CAGE ASSEMBLY & PARTS

P/N	DIM A	DIM B	DESCRIPTION	POWER LEVEL	THERMAL RESISTANCE @200 LFM
747360220	N/A	N/A	XFP CAGE WITH NO HEATSINK OR CLIP	N/A	N/A
747360221	4.0	4.2	XFP CAGE WITH PCI HEATSINK	UP TO 1.5W	<18.0 C/W
747360222	6.3	6.5	XFP CAGE WITH SAN HEATSINK (SHOWN)	UP TO 2.5W	<11.5 C/W
747360223	13.3	13.5	XFP CAGE WITH TALL HEATSINK	UP TO 3.5W	<8.0 C/W
747360230	N/A	N/A	HEATSINK CLIP ONLY	N/A	N/A
747360240	N/A	N/A	PCI HEATSINK ONLY	UP TO 1.5W	<18.0 C/W
747360241	N/A	N/A	SAN HEATSINK ONLY	UP TO 2.5W	<11.5 C/W
747360242	N/A	N/A	TALL HEATSINK ONLY	UP TO 3.5W	<8.0 C/W

SHOWN WITH OPTIONAL HEATSINK (SAN) AND CLIP



△1 MAXIMUM HEIGHT OF HEATSINK WITH MODULE INSERTED
△2 OVERALL HEIGHT OF HEATSINK
3. OTHER HEATSINK DESIGNS ARE AVAILABLE INCLUDING CUSTOM DESIGNS

REV	DESCRIPTION
F	ADDED NOTE PG 2 EC NO: USY2011-0296 2010/03/01 DRWN:JERWIN CH'KD:CHIRSCHY 2010/11/09 APPR:RMAHMOOD

QUALITY SYMBOLS
▼=0
▽C=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

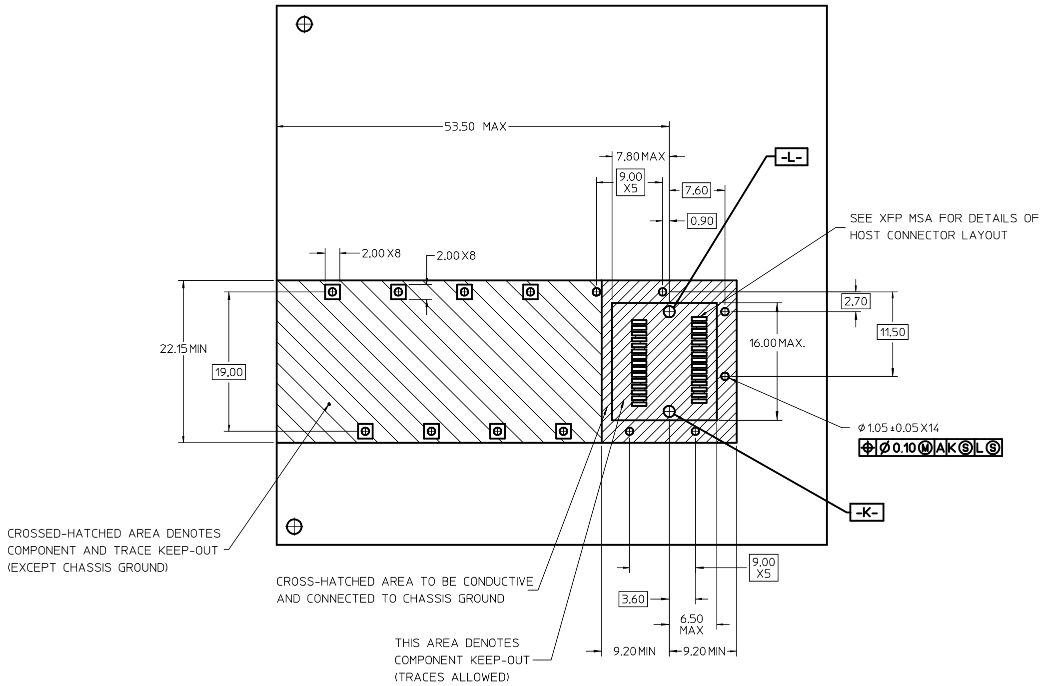
	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.10	± ---
1 PLACE	± 0.25	± ---

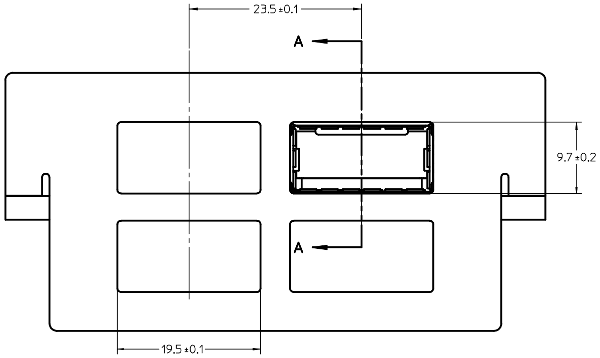
ANGULAR ± 1 °

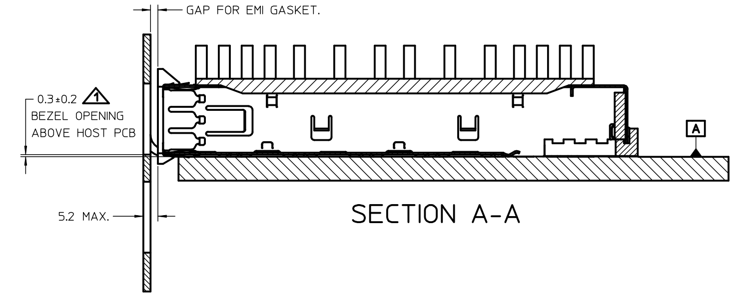
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	3:1
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY / DATE	KLLOYD 2004/05/14
CHECKED BY / DATE	BRUSSELL 2004/08/05
APPROVED BY / DATE	RMAHMOOD 2010/11/09
TITLE	XFP CAGE ASSEMBLY
MATERIAL NO.	SEE CHART
DOCUMENT NO.	SD-74736-220
SHEET NO.	1 OF 2
SIZE	D

MOLEX INCORPORATED







SECTION A-A

△1 **FOR PCI APPLICATIONS RECOMMENDED DIMENSION IS 0.4 ±0.1**

REV	DESCRIPTION
F	**ADDED NOTE PG 2** EC NO: USY2011-0296 2010/03/01 DRWN:JERWIN CH'KD:CHIRSCHY APPR:RMAHMOOD 2010/11/09

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.10	± ---
1 PLACE	± 0.25	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: **MM ONLY**
SCALE: **3:1**
DESIGN UNITS: **METRIC**
THIRD ANGLE PROJECTION

		DATE
DRAWN BY	KLLOYD	2004/05/14
CHECKED BY	BRUSSELL	2004/08/05
APPROVED BY	RMAHMOOD	2010/11/09

TITLE: XFP CAGE ASSEMBLY

MOLEX INCORPORATED

MATERIAL NO.: SEE CHART
DOCUMENT NO.: SD-74736-220
SHEET NO.: 2 OF 2
SIZE: D